



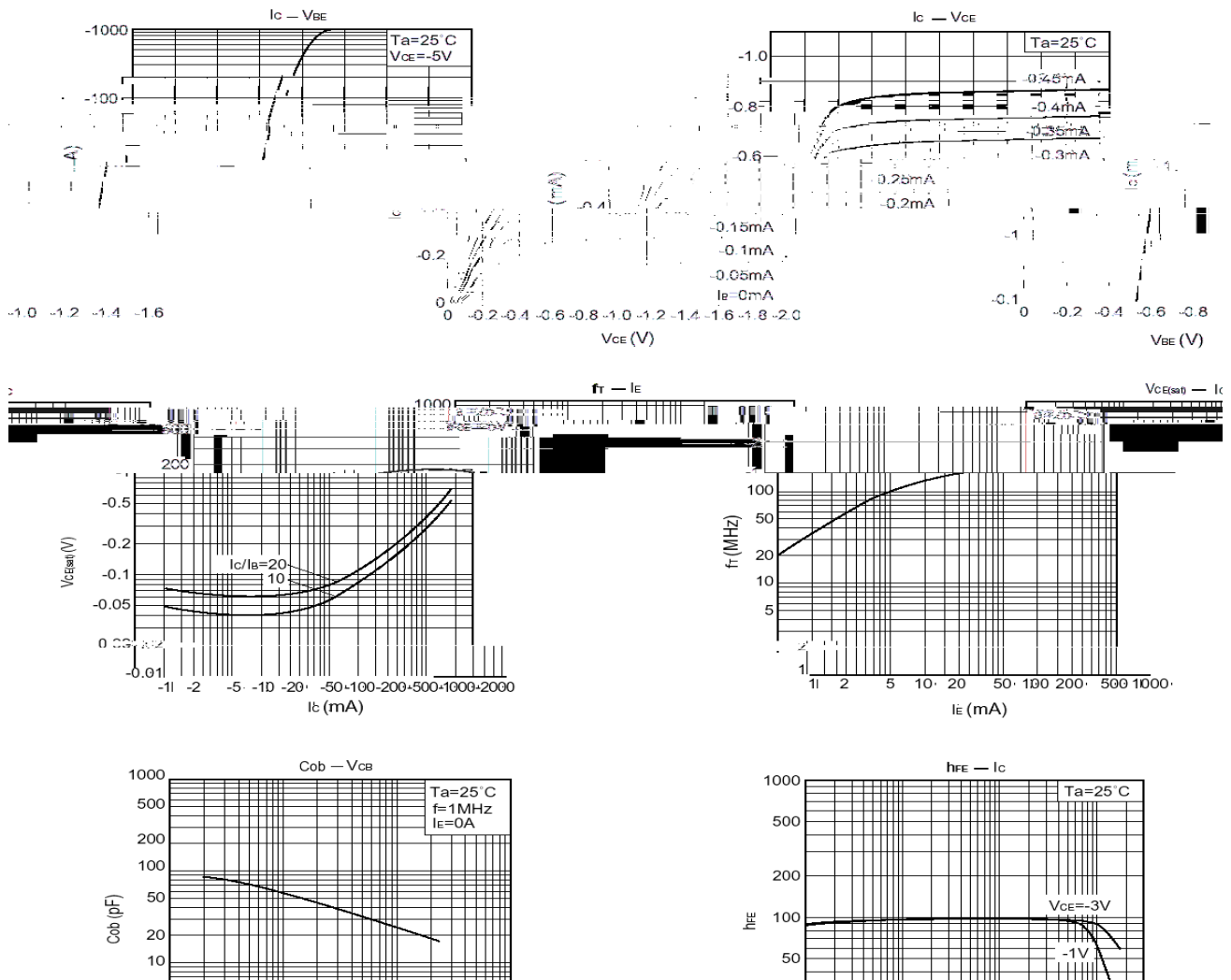
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-80	V
Collector to Emitter Voltage	V_{CEO}	-80	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current-Continuous	I_C	-1.0	A
Collector Current-Continuous(Pulse)	$*I_{CP}$	-2.0	A
Collector Power Dissipation	$**P_C$	0.5	W
	$*P_C$	2.0	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

*Single pulse $P_w=100ms$ $\leq 100ms$

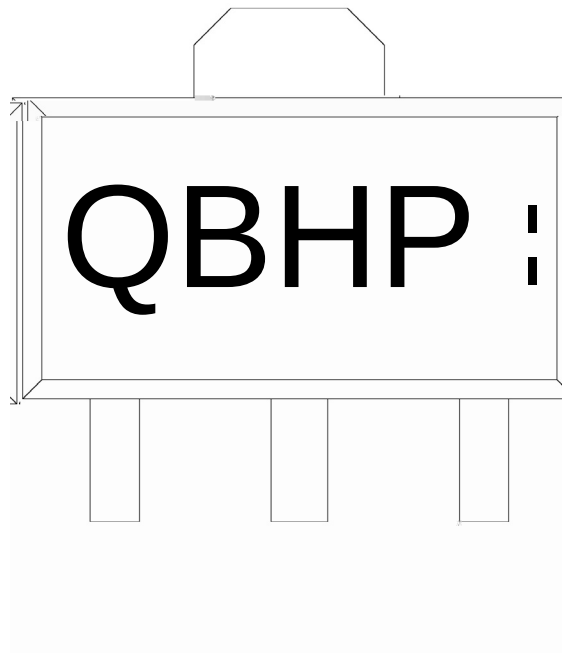
**mounted on $40 \times 40 \times 0.7mm$ ceramic board $40 \times 40 \times 0.7mm$ i

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C=-50\mu A$ $I_E=0$	-80			V
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=-1.0mA$ $I_B=0$	-80			V

/ Electrical Characteristic Curve



/ Marking Instructions



Q " X

T X 汽车产品代码

BH X 产品型号

P X h_{FE} 分类代码

-- X 生产批号

Note:

Q: Automobile halogen-free product Code

BH: Product Type

P X h_{FE} Classifications Symbol

** : Lot No. Code, code change with Lot No

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

℃

Note:

1. 150~200℃, Time: 60~120sec;

1.Preheating:150~200℃, Time:60~120sec.

2. 255±5℃, Time: 5~0.5sec;

2.Peak Temp.:255±5℃, Duration:5~0.5sec.

3. Cooling Speed: 2~10℃/sec.

3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

260±5℃

Time: 10±1 sec.

Temp.:260±5

Time:10±1 sec